



Precision Monolithic Quad SPST Low-Voltage CMOS Analog Switches

FEATURES

- 2.7- thru 12-V Single Supply or ± 3 - thru ± 6 -Dual Supply
- On-Resistance— $r_{DS(on)}$: 17 Ω
- Fast Switching— t_{ON} : 19 ns
— t_{OFF} : 12 ns
- TTL, CMOS Compatible
- Low Leakage: 0.25 nA
- 2000-V ESD Protection

BENEFITS

- Widest Dynamic Range
- Low Signal Errors and Distortion
- Break-Before-Make Switching Action
- Simple Interfacing

APPLICATIONS

- Precision Automatic Test Equipment
- Precision Data Acquisition
- Communication Systems
- Battery Powered Systems
- Computer Peripherals
- SDSL, DSLAM
- Audio and Video Signal Routing

DESCRIPTION

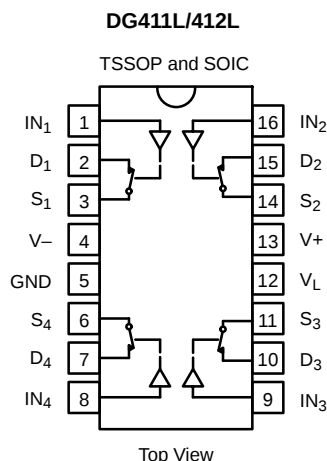
The DG411L/412L/413L are low voltage pin-for-pin compatible companion devices to the industry standard DG411/412/413 with improved performance

Using BiCMOS wafer fabrication technology allows the DG411L/412L/413L to operate on single and dual supplies. Single supply voltage ranges from 3 to 12 V while dual supply operation is recommended with ± 3 to ± 6 V.

Combining high speed (t_{ON} : 19 ns), flat $r_{DS(on)}$ over the analog signal range (5 Ω), minimal insertion loss (-3 dB at 280 MHz), and excellent crosstalk and off-isolation performance (-50 dB at 50 MHz), the DG411L/412L/413L are ideally suited for audio and video signal switching.

The DG411L and DG412L respond to opposite control logic as shown in the Truth Table. The DG413L has two normally open and two normally closed switches.

FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION

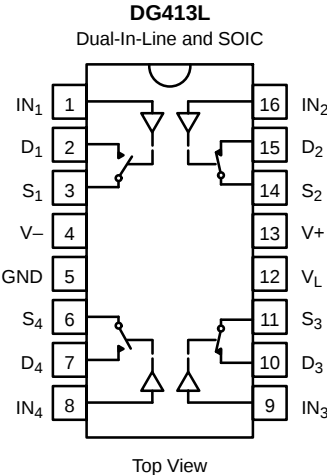


TRUTH TABLE		
Logic	DG411L	DG412L
0	ON	OFF
1	OFF	ON

Logic "0" ≤ 0.8 V
Logic "1" ≥ 2.4 V



FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION



TRUTH TABLE		
Logic	SW ₁ , SW ₄	SW ₂ , SW ₃
0	OFF	ON
1	ON	OFF

Logic "0" ≤ 0.8 V
Logic "1" ≥ 2.4 V

ORDERING INFORMATION		
Temp Range	Package	Part Number
DG411L/412L		
-40 to 85°C	16-Pin Narrow SOIC	DG411LDY
		DG412LDY
	16-Pin TSSOP	DG411LDQ
		DG412LDQ
DG413L		
-40 to 85°C	16-Pin Narrow SOIC	DG413LDY
	16-Pin TSSOP	DG413LDQ

ABSOLUTE MAXIMUM RATINGS

V+ to V- -0.3 TO 13 V
GND to V- 7 V
VL (GND -0.3 V) to (V+) +0.3 V
IN^a, VS, VD -0.3 to (V+ +0.3 V) or 30 mA, whichever occurs first
Continuous Current (Any Terminal) 30 mA
Peak Current, S or D (Pulsed 1 ms, 10% Duty Cycle) 100 mA
Storage Temperature (DQ, DY Suffix) -65 to 125°C

Power Dissipation (Package)^b
16-Pin TSSOP^c 450 mW
16-Pin SOIC^d 650 mW

- Notes:
- a. Signals on S_X, D_X, or IN_X exceeding V+ or V- will be clamped by internal diodes. Limit forward diode current to maximum current ratings.
 - b. All leads welded or soldered to PC Board.
 - c. Derate 7 mW/°C above 75°C
 - d. Derate 7.6 mW/°C above 75°C



SPECIFICATIONS ^a (SINGLE SUPPLY 12 V)							
Parameter	Symbol	Test Conditions Unless Specified V ⁺ = 12 V, V [–] = 0 V V _L = 5 V, V _{IN} = 2.4 V, 0.8 V ^f	Temp ^b	Limits –40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Analog Switch							
Analog Signal Range ^e	V _{ANALOG}		Full	0		12	V
Drain-Source On-Resistance	r _{DS(on)}	V ⁺ = 10.8 V, V [–] = 0 V I _S = –10 mA, V _D = 2/9 V	Room Full		20	30 40	Ω
Switch Off Leakage Current	I _{S(off)}	V _D = 11/11 V, V _S = 11/1 V	Room Full	–0.1 –2.5	± 0.01	0.1 2.5	nA
	I _{D(off)}		Room Full	–0.1 –2.5	± 0.01	0.1 2.5	
Channel On Leakage Current	I _{D(on)}	V _S = V _D = 11/1 V	Room Full	–0.2 –5	± 0.01	0.2 5	
Digital Control							
Input Current, V _{IN} Low	I _{IL}	V _{IN} Under Test = 0.8 V	Full	–1	0.01	1	μA
Input Current, V _{IN} High	I _{IH}	V _{IN} Under Test = 2.4 V	Full	–1		1	
Dynamic Characteristics							
Turn-On Time	t _{ON}	R _L = 300 Ω, C _L = 35 pF V _S = 5 V See Figure 2	Room Full		20	50 60	ns
Turn-Off Time	t _{OFF}		Room Full		12	30 40	
Break-Before-Make Time Delay	t _D	DG413L Only, V _S = 5 V R _L = 300 Ω, C _L = 35 pF	Room		6		
Charge Injection ^e	Q	V _g = 0 V, R _g = 0 Ω, C _L = 10 nF	Room		5		pC
Off Isolation ^e	OIRR	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz	Room		71		dB
Channel-to-Channel Crosstalk ^e	X _{TALK}		Room		95		
Source Off Capacitance ^e	C _{S(off)}	f = 1 MHz	Room		5		pF
Drain Off Capacitance ^e	C _{D(off)}		Room		6		
Channel On Capacitance ^e	C _{D(on)}		Room		15		
Power Supplies							
Positive Supply Current	I ⁺	V _{IN} = 0 or 5 V	Room Full		0.02	1 5	μA
Negative Supply Current	I [–]		Room Full	–1 –5	–0.002		
Logic Supply Current	I _L		Room Full		0.002	1 5	
Ground Current	I _{GND}		Room Full	–1 –5	–0.002		

SPECIFICATIONS ^a (DUAL SUPPLY ± 5 V)							
Parameter	Symbol	Test Conditions Unless Specified V ⁺ = 5 V, V [−] = −5 V V _L = 5 V, V _{IN} = 2.4 V, 0.8 V ^f	Temp ^b	Limits −40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Analog Switch							
Analog Signal Range ^e	V _{ANALOG}		Full	−5		5	V
Drain-Source On-Resistance	r _{DS(on)}	V ⁺ = 5 V, V [−] = −5 V I _S = −10 mA, V _D = ± 3.5 V	Room Full		20	30 40	Ω
Switch Off Leakage Current ^g	I _{S(off)}	V ⁺ = 5 V, V [−] = −5 V V _D = ± 4.5 V, V _S = ∓ 4.5 V	Room Full	−0.1 −2.5	± 0.01 ± 0.5	0.1 2.5	nA
	I _{D(off)}		Room Full	−0.1 −2.5	± 0.01	0.1 2.5	
Channel On Leakage Current ^g	I _{D(on)}	V ⁺ = 5 V, V [−] = −5 V V _S = V _D = ± 4.5 V	Room Full	−0.2 −5	± 0.01 ± 0.5	0.2 5	

SPECIFICATIONS ^a (DUAL SUPPLY ± 5 V)							
Parameter	Symbol	Test Conditions Unless Specified V ⁺ = 5 V, V [−] = −5 V V _L = 5 V, V _{IN} = 2.4 V, 0.8 V ^f	Temp ^b	Limits −40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Digital Control							
Input Current, V _{IN} Low ^e	I _{IL}	V _{IN} Under Test = 0.8 V	Full	−1	0.05	1	μA
Input Current, V _{IN} High ^e	I _{IH}	V _{IN} Under Test = 2.4 V	Full	−1	0.05	1	
Dynamic Characteristics							
Turn-On Time	t _{ON}	R _L = 300 Ω, C _L = 35 pF V _S = ±3.5 V See Figure 2	Room Full		21	50 60	ns
Turn-Off Time	t _{OFF}		Room Full		16	35 40	
Break-Before-Make Time Delay ^e	t _D	DG413L Only, V _S = 3.5 V R _L = 300 Ω, C _L = 35 pF	Room		6		
Charge Injection ^e	Q	V _g = 0 V, R _g = 0 Ω, C _L = 10 nF	Room		5		pC
Off Isolation ^e	OIRR	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz	Room		68		dB
Channel-to-Channel Crosstalk ^e	X _{TALK}		Room		85		
Source Off Capacitance ^e	C _{S(off)}	f = 1 MHz	Room		9		pF
Drain Off Capacitance ^e	C _{D(off)}		Room		9		
Channel On Capacitance ^e	C _{D(on)}		Room		20		
Power Supplies							
Positive Supply Current ^e	I ⁺	V _{IN} = 0 or 5 V	Room Full		0.03	1 5	μA
Negative Supply Current ^e	I [−]		Room Full	−1 −5	−0.002		
Logic Supply Current ^e	I _L		Room Full		0.002	1 5	
Ground Current ^e	I _{GND}		Room Full	−1 −5	−0.002		

SPECIFICATIONS ^a (SINGLE SUPPLY 5 V)							
Parameter	Symbol	Test Conditions Unless Specified V ⁺ = 5 V, V ⁻ = 0 V V _L = 5 V, V _{IN} = 2.4 V, 0.8 V ^f	Temp ^b	Limits -40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Analog Switch							
Analog Signal Range ^e	V _{ANALOG}		Full			5	V
Drain-Source On-Resistance ^e	r _{DS(on)}	V ⁺ = 4.5 V, I _S = -5 mA V _D = 1 V, 3.5 V	Room Full		35	50 75	Ω
Dynamic Characteristics							
Turn-On Time ^e	t _{ON}	R _L = 300 Ω, C _L = 35 pF V _S = 3.5 V, See Figure 2	Room Hot		27	50 60	ns
Turn-Off Time ^e	t _{OFF}		Room Hot		15	30 40	
Break-Before-Make Time Delay ^e	t _D	DG413L Only, V _S = 3.5 V, R _L = 300 Ω, C _L = 35 pF	Room		6		
Charge Injection ^e	Q	V _g = 0 V, R _g = 0 Ω, C _L = 10 nF	Room		0.5		pC

**SPECIFICATIONS^a (SINGLE SUPPLY 5 V)**

Parameter	Symbol	Test Conditions Unless Specified V+ = 5 V, V– = 0 V VL = 5 V, VIN = 2.4 V, 0.8 V ^f	Temp ^b	Limits –40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Power Supplies							
Positive Supply Current ^e	I+	VIN = 0 or 5 V	Room Hot		0.02	1 5	µA
Negative Supply Current ^e	I–		Room Hot	–1 –5	–0.002		
Logic Supply Current ^e	IL		Room Hot		0.002	1 5	
Ground Current ^e	IGND		Room Hot	–1 –5	–0.002		

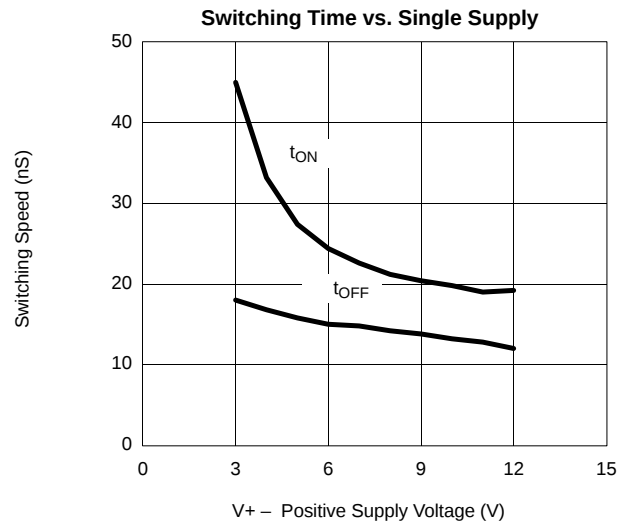
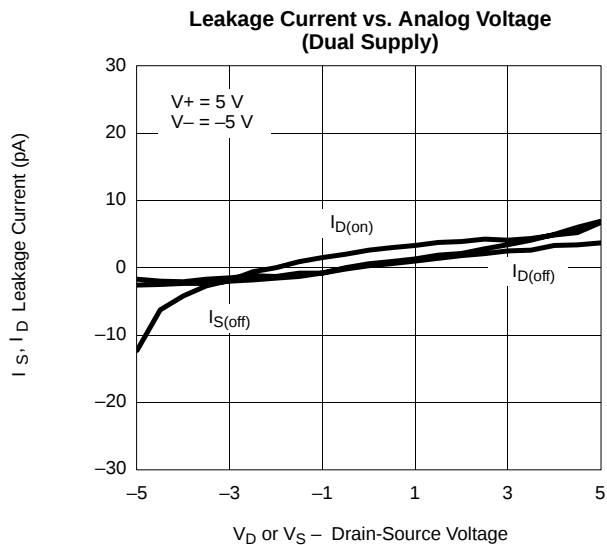
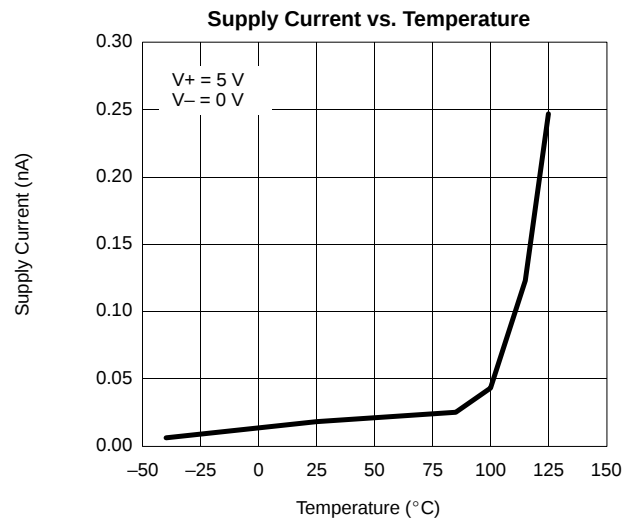
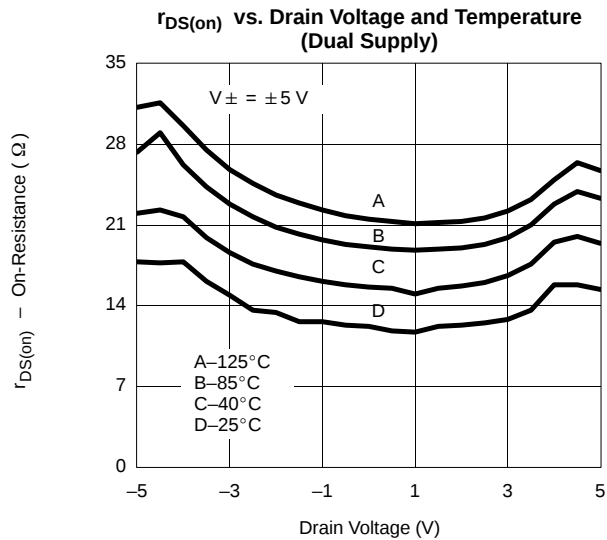
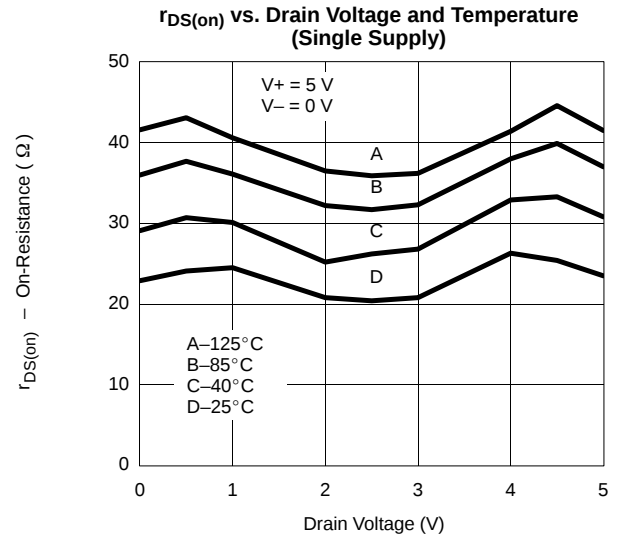
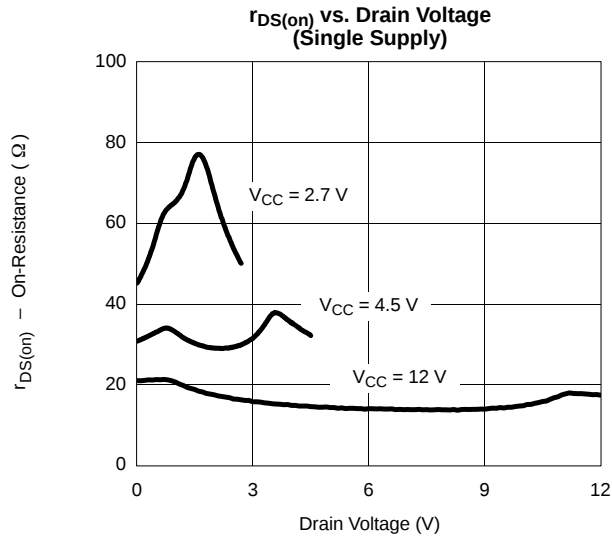
SPECIFICATIONS^a (SINGLE SUPPLY 3 V)

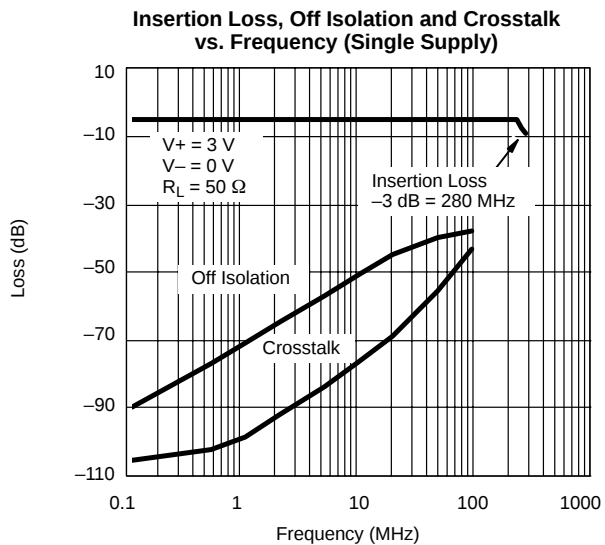
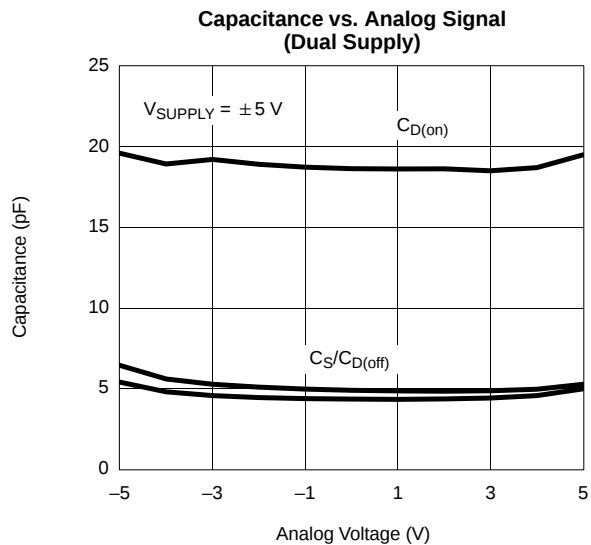
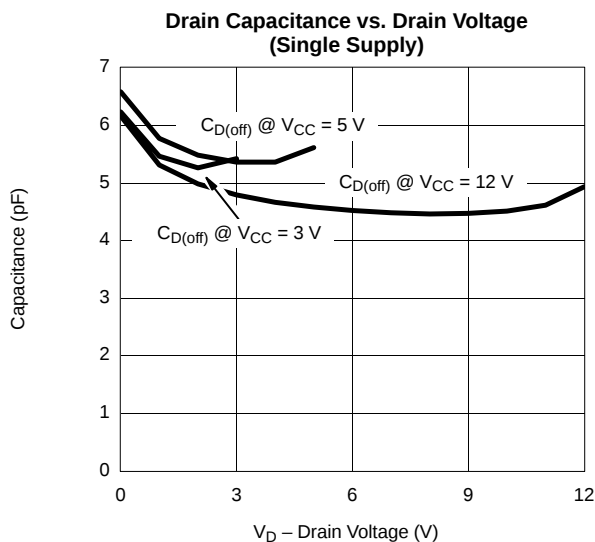
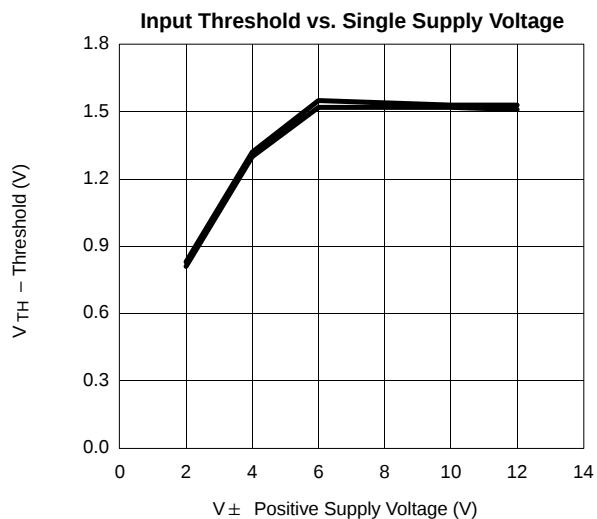
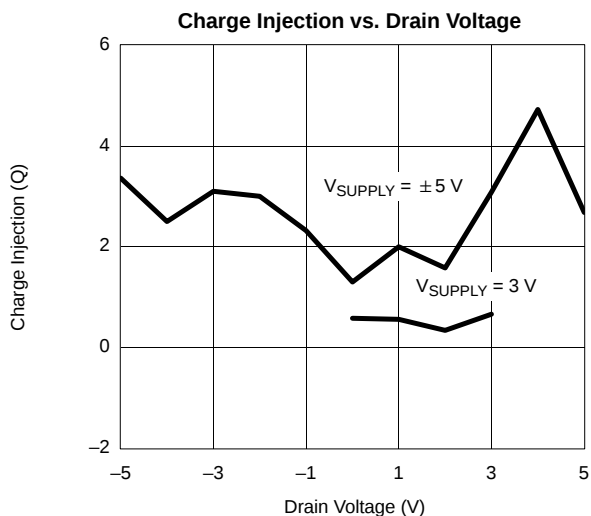
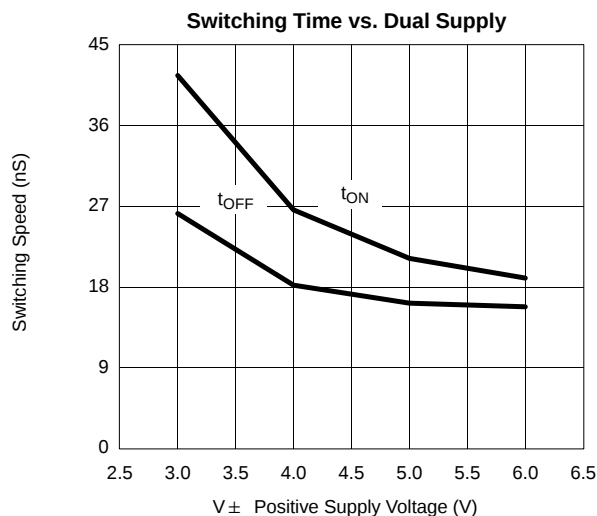
Parameter	Symbol	Test Conditions Unless Specified V+ = 3 V, V– = 0 V V _L = 3 V, V _{IN} = 0.4 V ^f	Temp ^b	Limits –40 to 85°C			Unit
				Min ^d	Typ ^c	Max ^d	
Analog Switch							
Analog Signal Range ^e	V _{ANALOG}		Full	0		3	V
Drain-Source On-Resistance	r _{DS(on)}	V+ = 2.7 V, V– = 0 V I _S = –10 mA, V _D = 0.5, 2.2 V	Room Full		65	80 100	Ω
Switch Off Leakage Current ^g	I _{S(off)}	V+ = 3 V, V– = 0 V V _D = 1, 2 V, V _S = 2, 1 V	Room Full	–0.1 –2.5	± 0.01	0.1 2.5	nA
	I _{D(off)}		Room Full	–0.1 –2.5	± 0.01	0.1 2.5	
Channel On Leakage Current ^g	I _{D(on)}	V+ = 3 V, V– = 0 V V _S = V _D = 1, 2 V	Room Full	–0.2 –5	± 0.01	0.2 5	
Digital Control							
Input Current, V _{IN} Low	I _{IL}	V _{IN} Under Test = 0.4 V	Full	–1	0.005	1	μA
Input Current, V _{IN} High	I _{IH}	V _{IN} Under Test = 2.4 V	Full	–1	0.005	1	
Dynamic Characteristics							
Turn-On Time	t _{ON}	R _L = 300 Ω, C _L = 35 pF V _S = 1.5 V See Figure 2	Room Full		50	85 110	ns
Turn-Off Time	t _{OFF}		Room Full		30	60 85	
Break-Before-Make Time Delay	t _D	DG413L Only, V _S = 1.5 V R _L = 300 Ω, C _L = 35 pF	Room		6		
Charge Injection ^e	Q	V _g = 0 V, R _g = 0 Ω, C _L = 10 nF	Room		1		pC
Off Isolation ^e	OIRR	R _L = 50 Ω, C _L = 5 pF, f = 1 MHz	Room		68		dB
Channel-to-Channel Crosstalk ^e	X _{TALK}		Room		85		
Source Off Capacitance ^e	C _{S(off)}	f = 1 MHz	Room		6		pF
Drain Off Capacitance ^e	C _{D(off)}		Room		6		
Channel On Capacitance ^e	C _{D(on)}		Room		20		

Notes:

- Refer to PROCESS OPTION FLOWCHART.
- Room = 25°C, Full = as determined by the operating temperature suffix.
- Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
- The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.
- Guaranteed by design, not subject to production test.
- V_{IN} = input voltage to perform proper function.
- Leakage parameters are guaranteed by worst case test conditions and not subject to test.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**



SCHEMATIC DIAGRAM (TYPICAL CHANNEL)

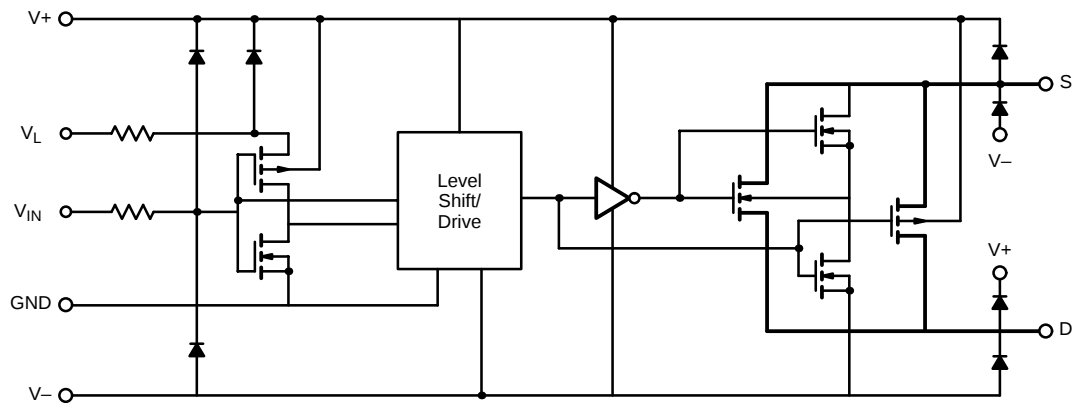
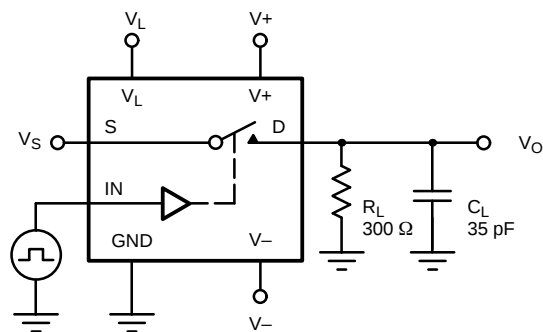


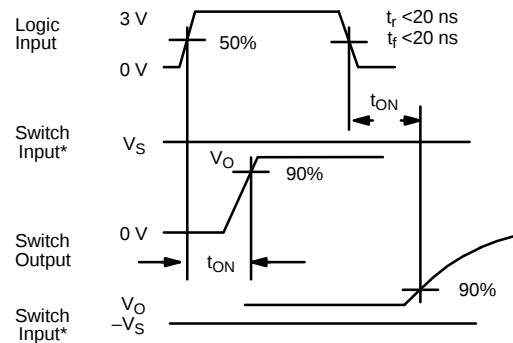
FIGURE 1.

TEST CIRCUITS



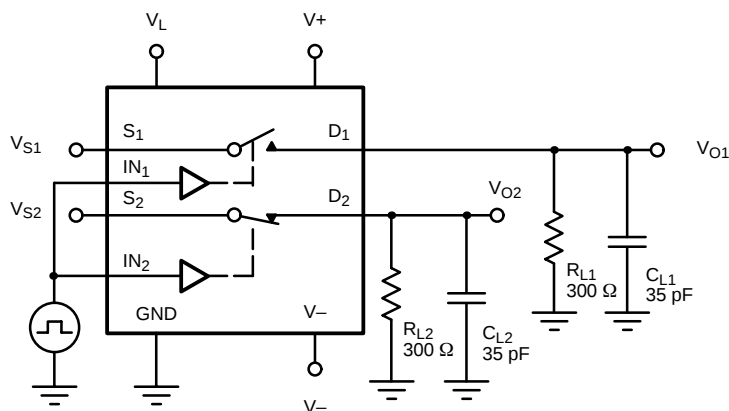
C_L (includes fixture and stray capacitance)

$$V_O = V_S \frac{R_L}{R_L + r_{DS(on)}}$$



Note: Logic input waveform is inverted for switches that have the opposite logic sense control

FIGURE 2. Switching Time



C_L (includes fixture and stray capacitance)

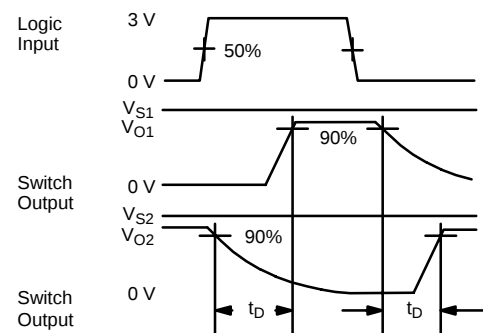


FIGURE 3. Break-Before-Make (DG413L)

TEST CIRCUITS

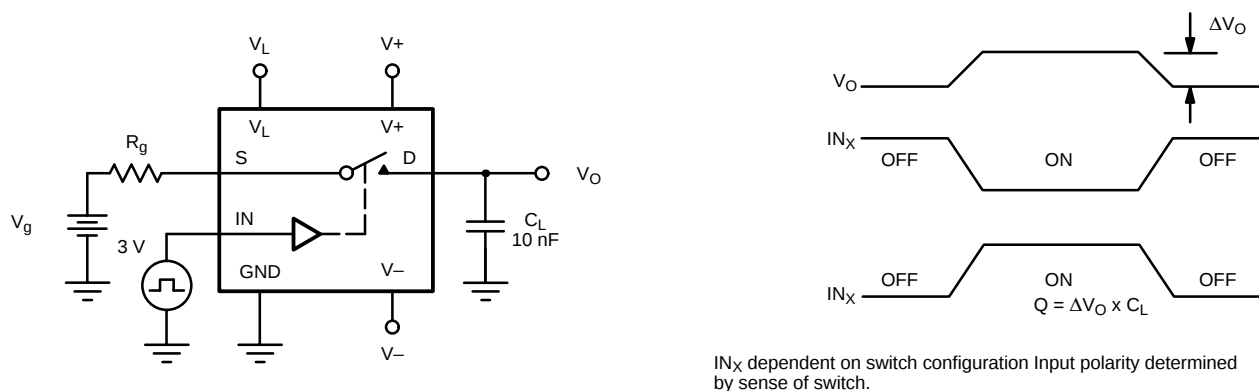


FIGURE 4. Charge Injection

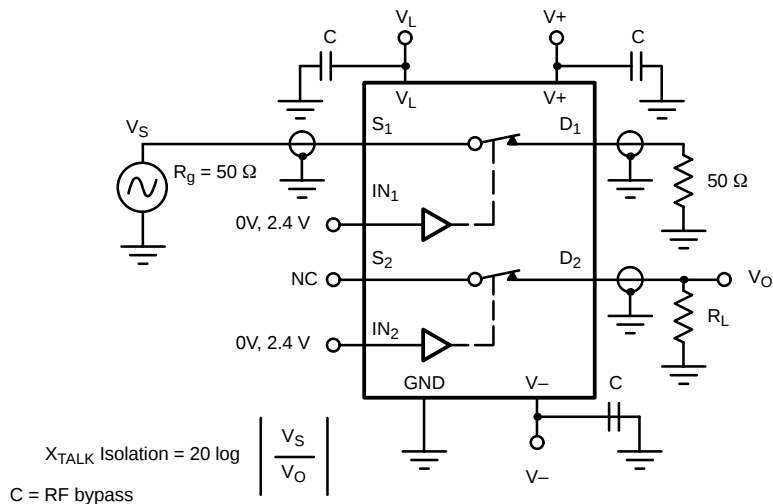


FIGURE 5. Crosstalk

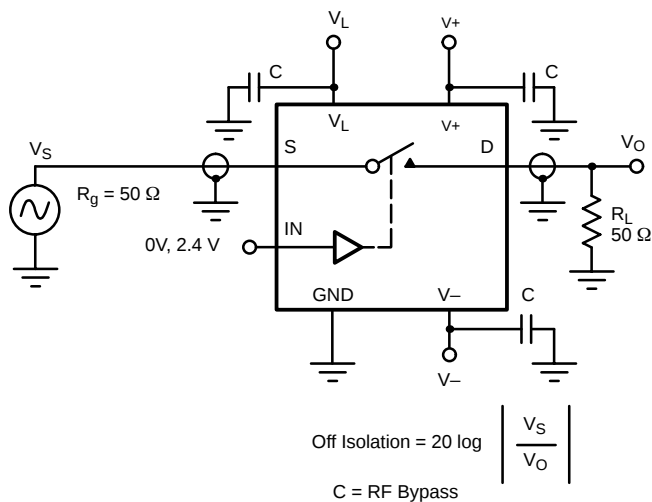


FIGURE 6. Off Isolation

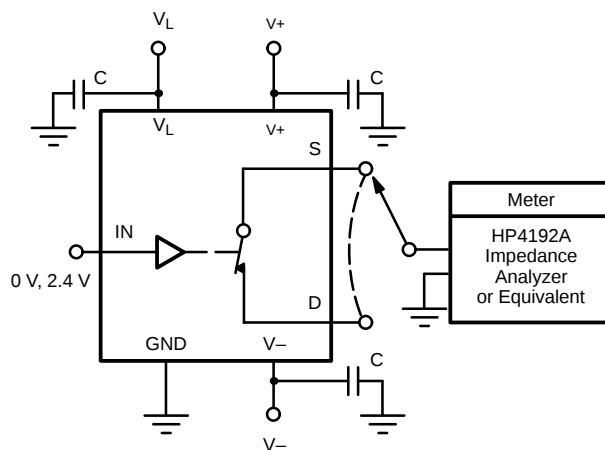


FIGURE 7. Source/Drain Capacitances